

3A Avg.

35 Volts

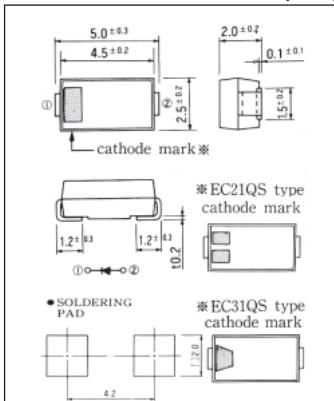
SBD

EC30QSA035

■最大定格 Maximum Ratings

Item	Symbol	Conditions		Unit	
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	35		V	
平均整流電流 Average Rectified Forward Current	I_O	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	$T_a=25^{\circ}\text{C}^*$ $V_{RM}=15\text{V}$	1.9	A
			$T_l=103^{\circ}\text{C}$ $V_{RM}=15\text{V}$ (T_l :lead Temperature)	3.0	A
実効順電流 R.M.S. Forward Current	$I_{F(RMS)}$	4.71		A	
サージ順電流 Surge Current	I_{FSM}	60		A	
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150		$^{\circ}\text{C}$	
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150		$^{\circ}\text{C}$	

■OUTLINE DRAWING(mm)



■APPROX. NET WEIGHT:0.06 g

■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions		Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^{\circ}\text{C}$, $V_{RM}=35\text{V}$		—	—	2	mA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^{\circ}\text{C}$, $I_{FM}=3\text{A}$		—	—	0.47	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	* (アルミナ基板実装)	—	—	108	$^{\circ}\text{C}/\text{W}$
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	—	23	$^{\circ}\text{C}/\text{W}$

*アルミナ基板実装/Alumina Substrate mounted (Soldering Lands=2×2 mm, Both Sides)

■定格・特性曲線

